

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJ3139KB
Package Type :	SOT-723

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	3.62%
Lead Frame	Copper	7440-50-8	96.38%	39.28%
	Silicon	7439-89-6	0.20%	
	Nickel	7723-14-0	1.20%	
	Tin	7440-66-6	1.70%	
	Zinc	7439-92-1	0.50%	
	Silver	7440-22-4	0.02%	
Wire	Copper	7440-50-8	98.00%	2.42%
	Palladium	7440/5/3	1.75%	
	Gold	7440-57-5	0.20%	
	Others	/	0.05%	
Mold Compound	Silica	60676-86-0	78.50%	53.91%
	Epoxy Resin	29690-82-2	11.00%	
	Phenolic Resin	9003-35-4	10.00%	
	Carbon Black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	99.90%	0.77%
	Other	/	0.10%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.